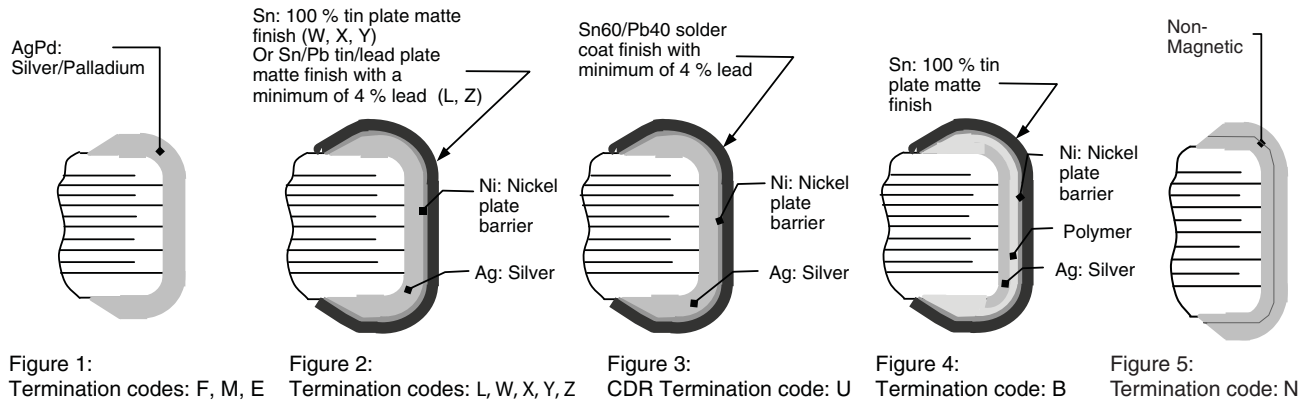


Vishay Vitramon MLCC End Termination



TERMINATION CODE FROM PART NUMBERING	TERMINATION DEFINITION	ACCEPTED ASSEMBLY METHODS
F, M ⁽³⁾	Fired, thick film, silver/palladium	Conductive epoxy/reflow solder
E ⁽²⁾	Fired, thick film, silver/palladium	Conductive epoxy
N	Fired, thick film, non magnetic material	Conductive epoxy/reflow solder ⁽⁵⁾
W ⁽³⁾ , X, Y ⁽³⁾	Fired, thick film silver, covered by 100 % nickel barrier plate with an outer layer of 100 % tin plate matte finish for multi-solder mounting	Wave solder ⁽¹⁾ /reflow solder/vapor phase reflow
L, Z ⁽³⁾	Fired, thick film silver, cover by 100 % nickel barrier plate with an outer layer of tin/lead plate matte finish with a minimum of 4 % lead for multi-solder mounting	Wave solder ⁽¹⁾ /reflow solder/vapor phase reflow
U ⁽⁴⁾	Fired, thick film silver, cover by 100 % nickel barrier plate with an outer layer of tin/lead plate finish matte with a minimum of 4 % lead for Sn60/Pb40 solder coat	Wave solder ⁽¹⁾ /reflow solder/vapor phase reflow
B	Fired, thick film silver, cured thick film polymer silver, covered by 100 % nickel barrier plate with an outer layer of 100 % tin plate matte finish for multi-solder mounting	Wave solder ⁽¹⁾ /reflow solder/vapor phase reflow

Notes

- (1) Case sizes 1210 to 1812 with a thickness > 0.049" (1.24 mm) and case sizes 1825 and larger should NOT be wave solder.
- (2) Termination code "E" is for conductive epoxy assembly, contact mlcc@vishay.com for availability
- (3) CDR and DSCC part numbers only.
- (4) CDR "U" termination code: Base metallization-barrier metal-solder coated (tin/lead alloy, with a minimum of 4 % lead). Solder has a melting point of + 200 °C or less. Solder coat thickness is a minimum of 60 microinches.
 - Solder iron techniques are not recommended. For more information on soldering visit www.vishay.com/doc245034
 - Contact mlcc@vishay.com with respect to specific part number requirements.
- (5) Non-magnetic terminations may exhibit high wetting angles and lower fillet heights as compared to barrier plate terminations such as X-term.

Vishay Vitramon MLCC End Termination

MLCC END TERMINATION PHYSICAL CHARACTERISTICS							
P/N TERM CODE	THICK FILM END TERMINATION		BARRIER TERMINATION	TERMINATION FINISH			
	MATERIAL	THICKNESS (inches)	Ni PLATE THICKNESS (microinches)	Sn PLATE THICKNESS (microinches)	Sn/Pb PLATE THICKNESS (microinches)	Sn/Pb SOLDER COAT THICKNESS (microinches)	CONTENT OF LEAD
F, M	Ag/Pd	0.001 min.	n/a	n/a	n/a	n/a	n/a
E	Ag/Pd	0.001 min.	n/a	n/a	n/a	n/a	n/a
N	Ag/Pd	0.0012 min.	n/a	n/a	n/a	n/a	n/a
W, X, Y	Ag	0.001 min.	50 min.	100 min.	n/a	n/a	n/a
L, Z	Ag	0.001 min.	50 min.	n/a	100 min.	n/a	4 % min.
U	Ag	0.001 min.	50 min.	n/a	n/a	60 min.	4 % min.
B	Polymer	0.003 min.	50 min.	100 min.	n/a	n/a	n/a

Notes

- Element definition: Ag = Silver, Pd = Palladium, Ni = Nickel, Sn = Tin, Pb = Lead
- N/A = Not applicable